

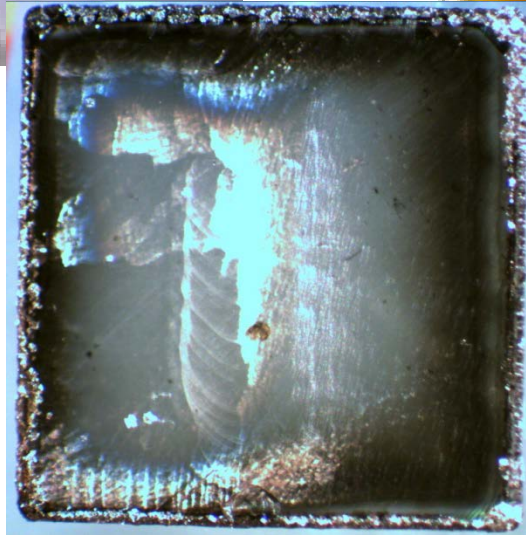
# Thin Diamond Time-of-Flight Detectors

Joseph Tabeling and Evan Kimberly

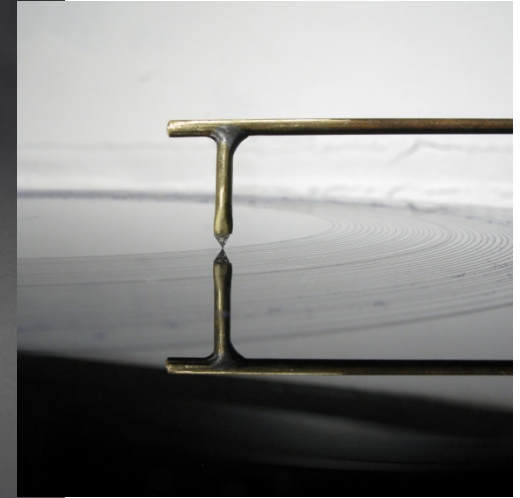
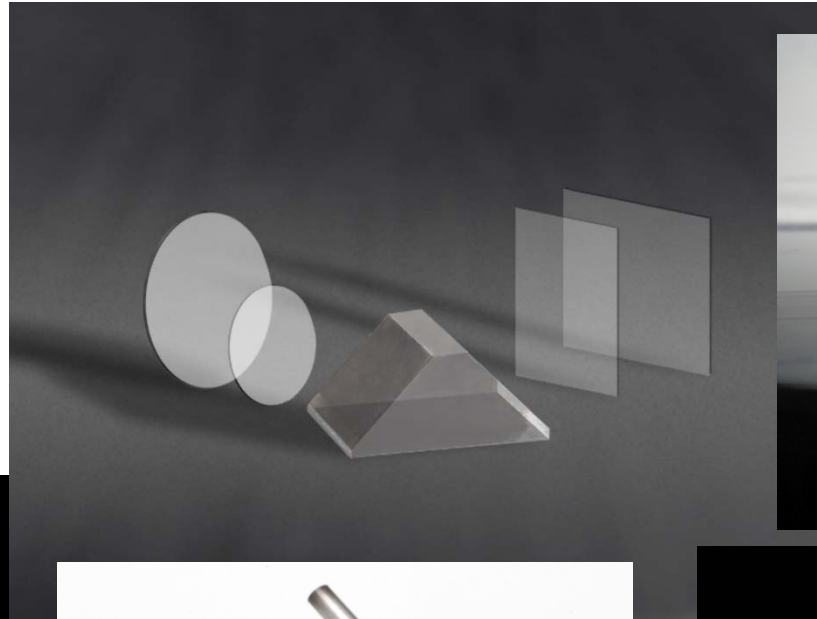
# Outline

- A bit about Applied Diamond
- Topic and Challenges
- Progress to-date
  - Diamond Growth
  - Material Removal
  - TOF Testing
  - Characterization
  - Packaging
- Commercialization

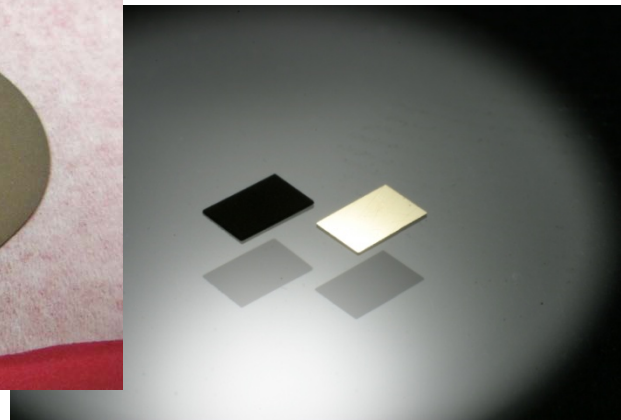
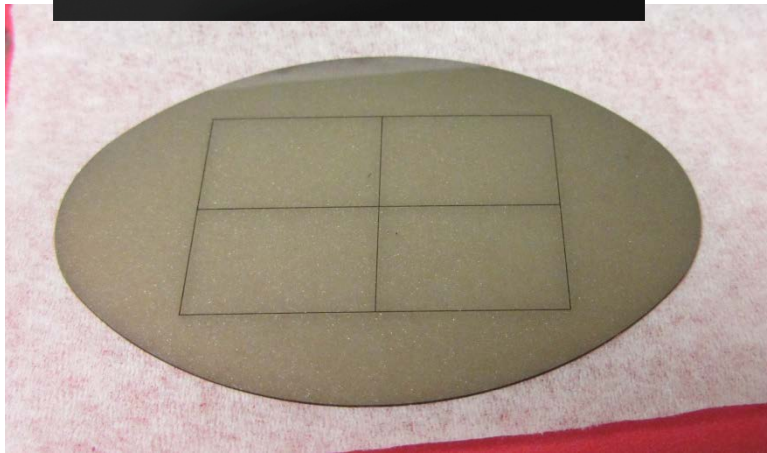
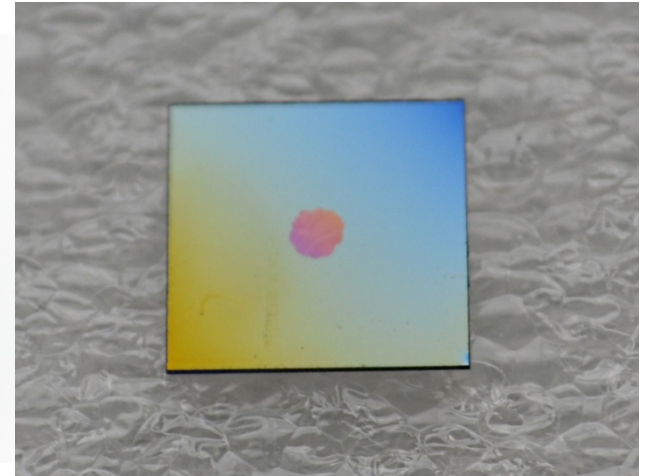
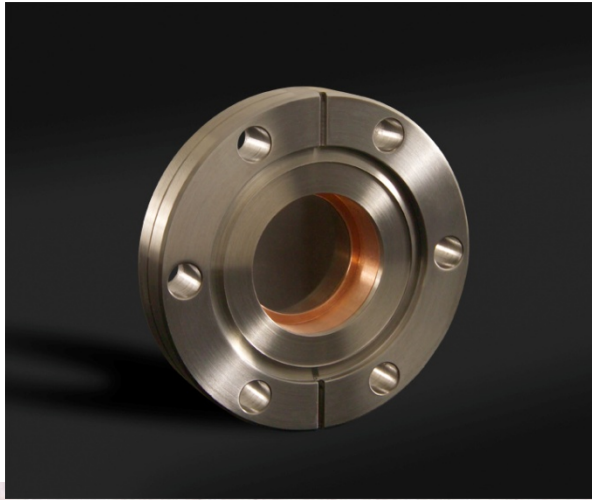
# Diamond – Types and Sources



# Diamond – Finished Products (single crystal)



# Diamond – Finished Products (polycrystalline)



# Solicitation Topic and Challenges

Future rare isotope beam facilities like FRIB will provide beams with unprecedented intensity, creating a challenge for single particle tracking and beam profile measurements. The development of position sensitive fast particle detectors for particle tracking/timing and with high rate capability would be desirable. Ideally these detectors would provide both position and timing measurements in a transmission mode and be radiation resistant and of very homogenous density and thickness.

Time-of-Flight Detectors – square cm, segmented

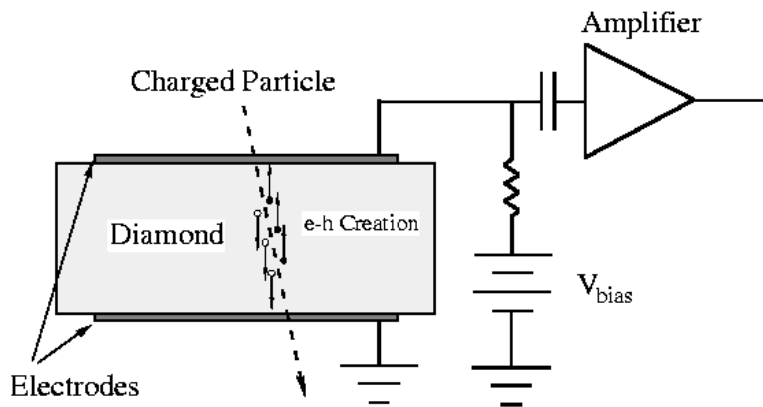
Focal Plane Array Detector – 20 cm x 2 cm, segmented

Uniform quality providing adequate S/N

Uniform mass (thickness and density)

Transmission mode = as thin as possible

# Why Diamond?



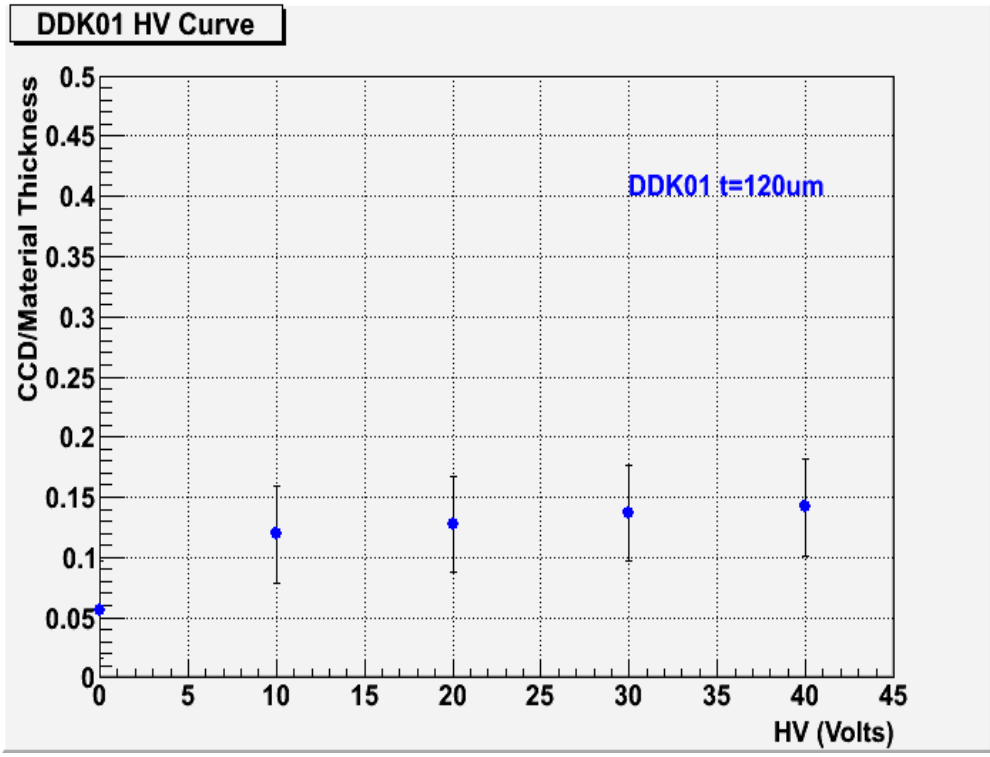
## Solid-State Ionization Chamber

- 36 e-h pairs created per  $\mu\text{m}$  of diamond traversed per MIP
- Charges drift responding to bias voltage creating measured signal
- Trapped by defects in material so charge collection distance is average distance an e-h pair drift apart

- Radiation hardness tested and found superior with wide range of particles/conditions.
- Smaller dielectric constant provides lower capacitance and lower noise.
- Very high thermal conductivity so managing thermal load is easier.

# Diamond Growth Progress

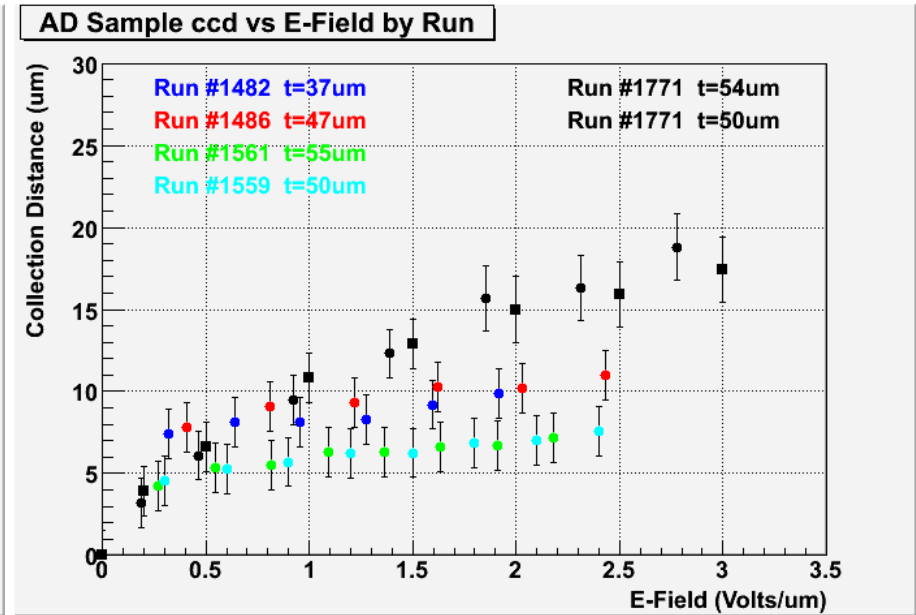
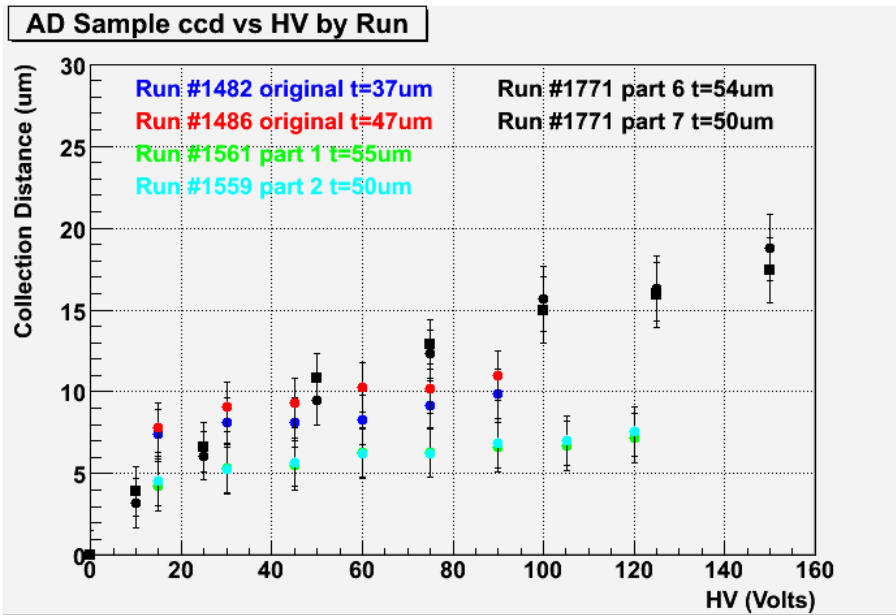
Early results on 100 $\mu\text{m}+$  films





# Diamond Growth Progress

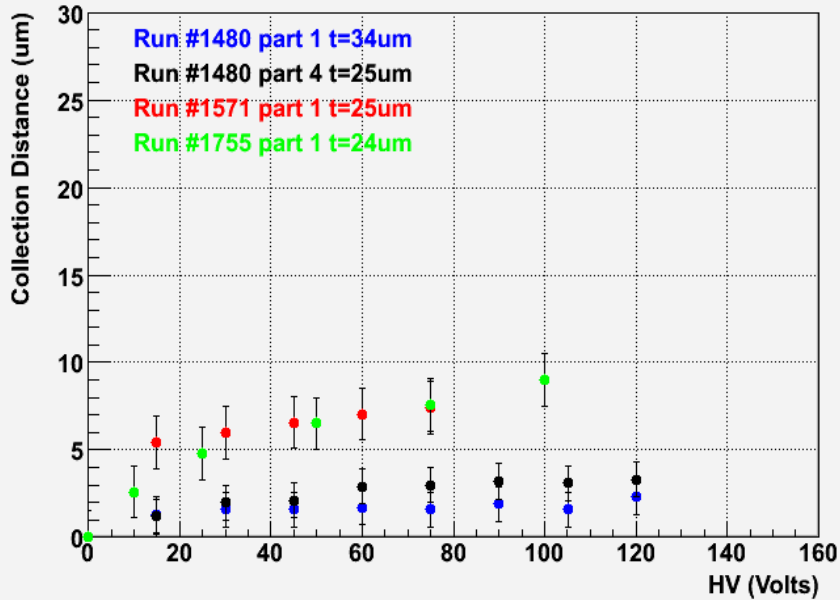
Early vs. current results on 50 – 60  $\mu\text{m}$  films



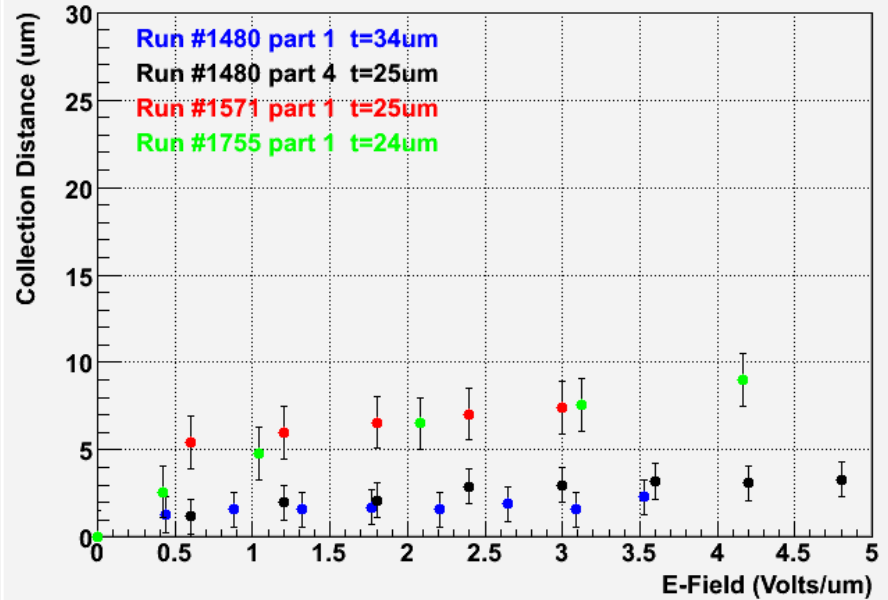
# Diamond Growth Progress

Early vs. current results on 25 – 30  $\mu\text{m}$  films

AD Sample ccd vs HV by Run

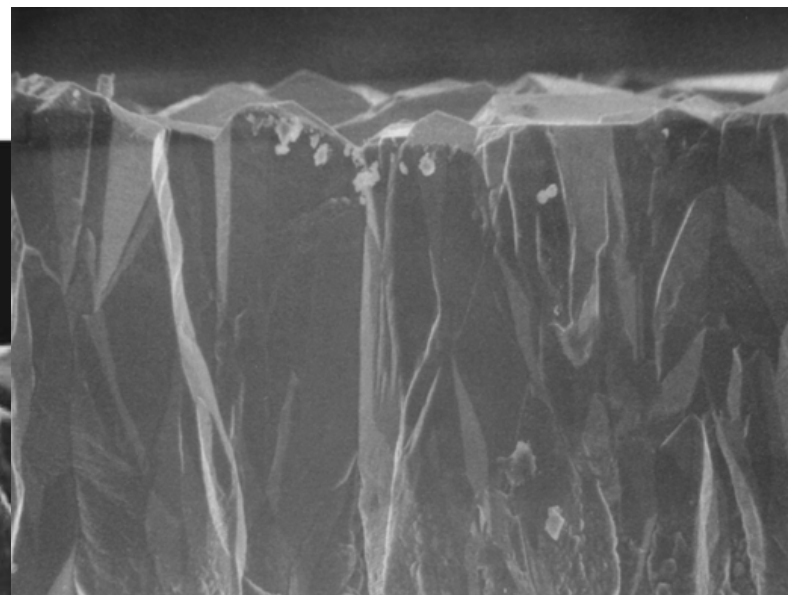
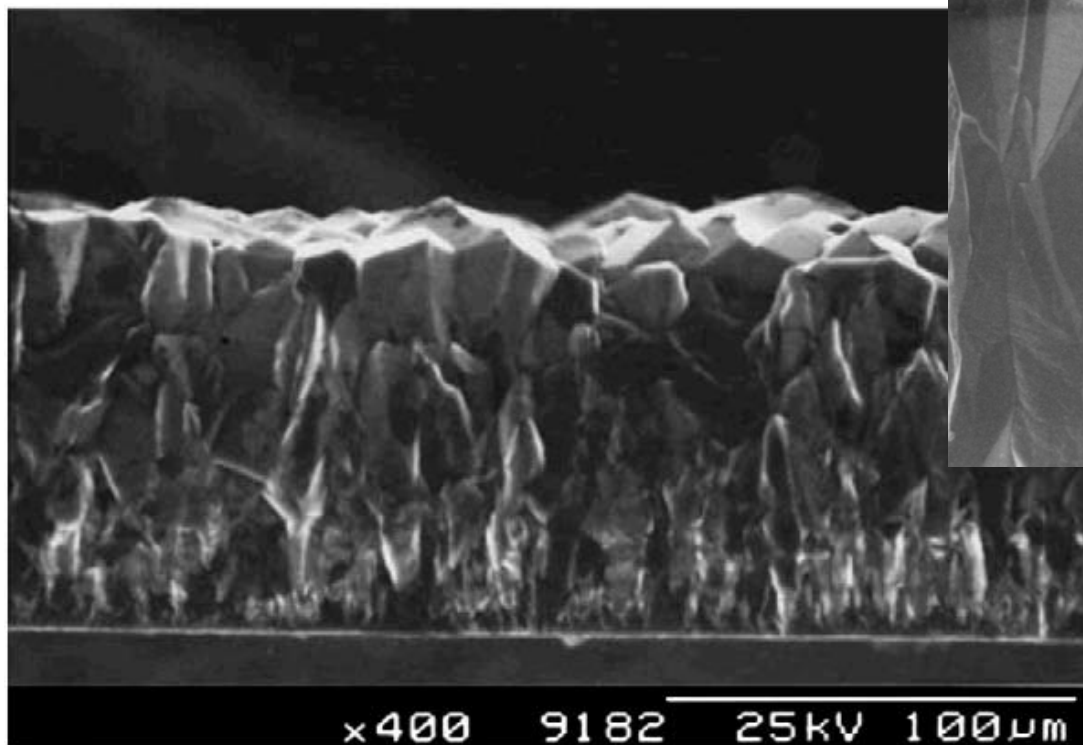


AD Sample ccd vs E-Field by Run



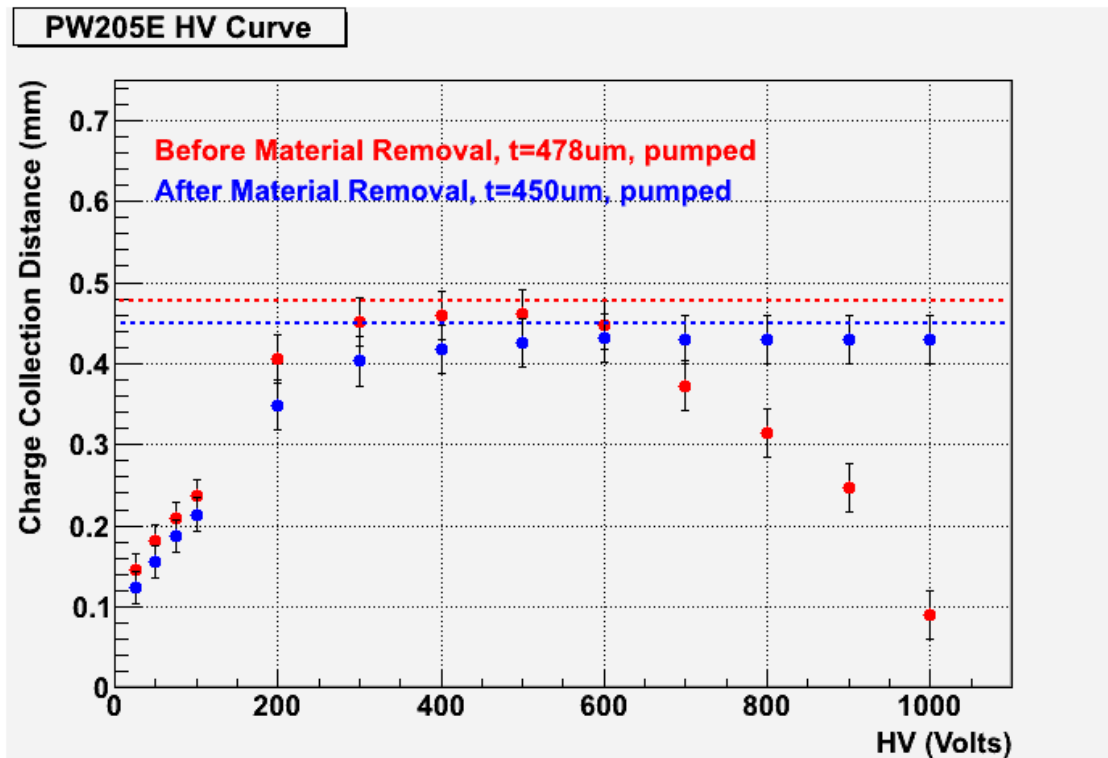
# Material Removal Progress

Why remove material?



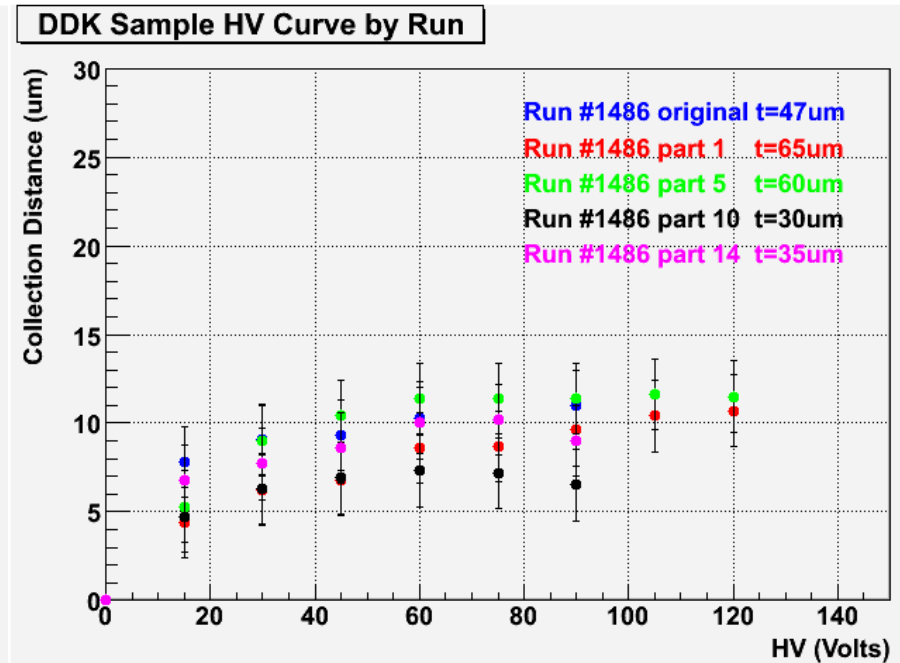
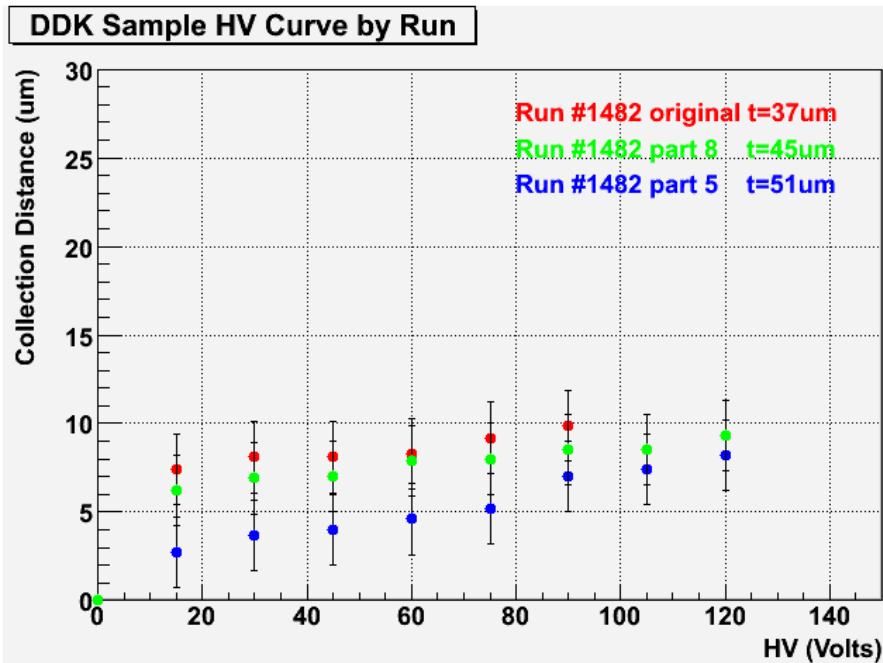
# Material Removal Progress

Early results - scCVD



# Material Removal Progress

Various methods on polyCVD – cont.



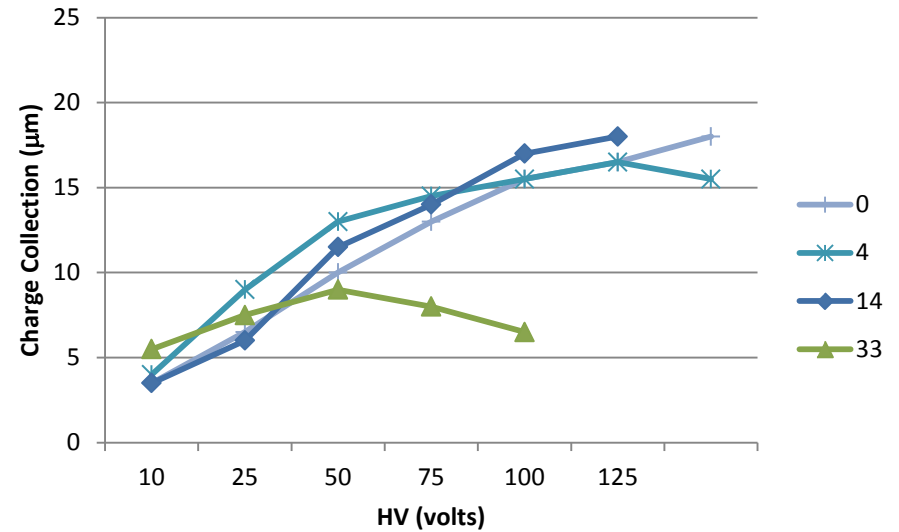
# Material Removal Progress

Thickness control by subtraction



... without affecting performance

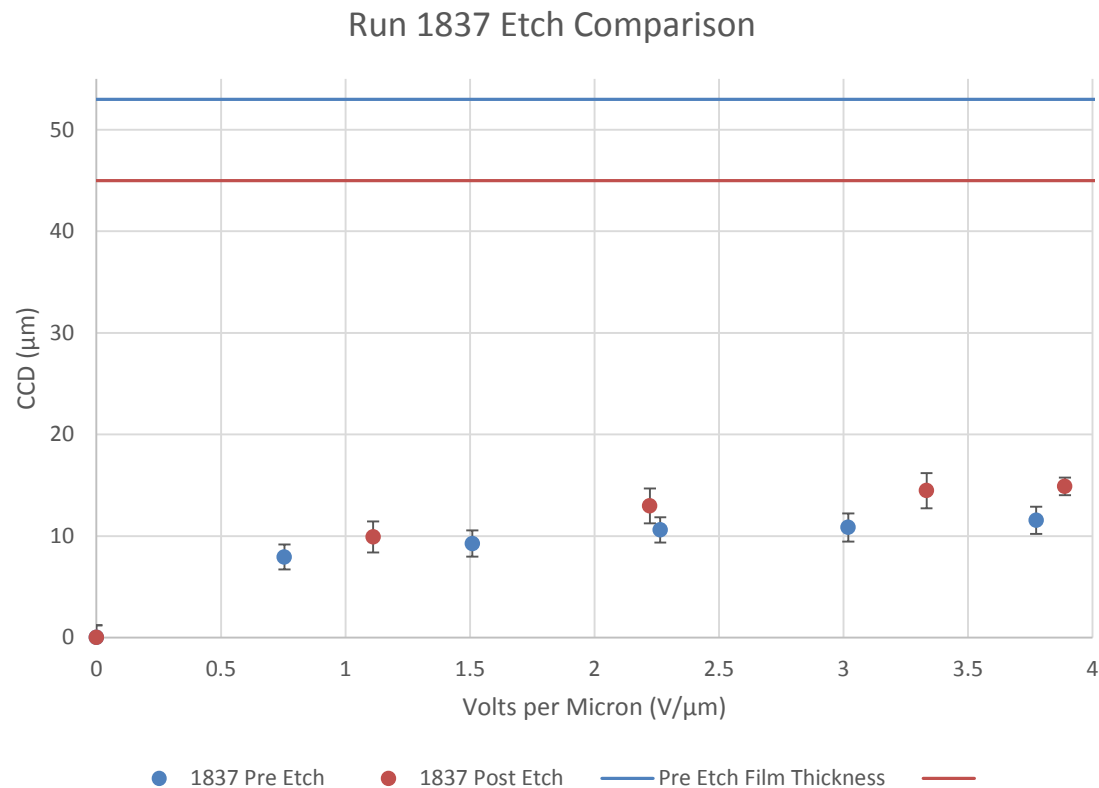
Fine control of thickness ...



DOE NP SBIR/STTR Exchange Meeting  
August 6 & 7, 2015

# Material Removal Progress

## Effect of back-etching on CCD



# Time-of-Flight Results

$^{232}\text{U}$  alpha particles with energy  
of 5.3MeV.

Bias = 100V

Leakage < 1 nA

Rise time ~ 0.8 ns

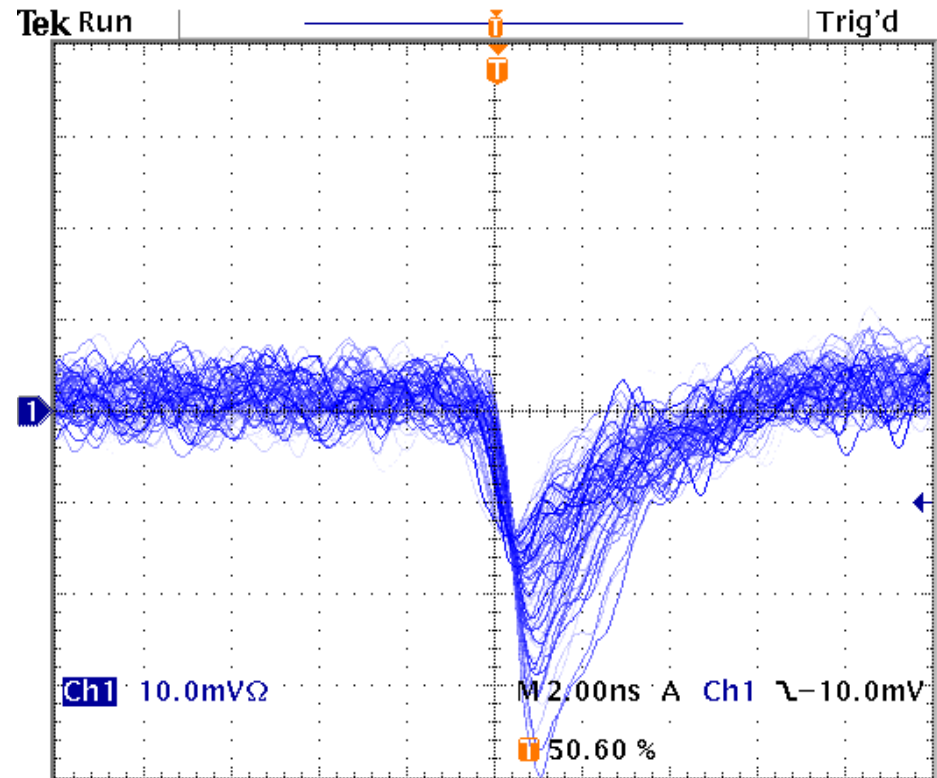
Decay/rise time ~ 3:1

S/N ~ 5

With 100 MeV/u particles,  
energy loss of:

11.4 MeV with  $^{20}\text{Ne}$

798 MeV with  $^{238}\text{U}$





# Time-of-Flight Results

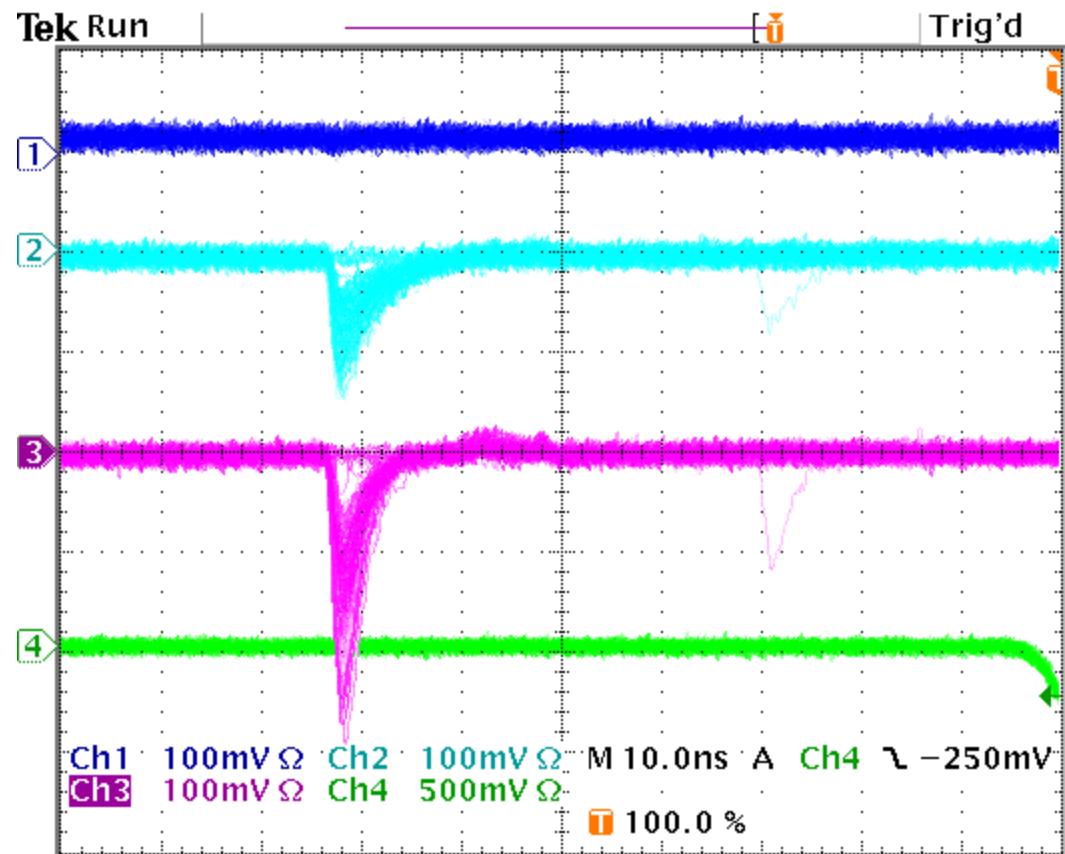
$^{40}\text{Ca}$  beam with energy  
of 140MeV/u.

- 1 – 65  $\mu\text{m}$  thick
- 2 – 60  $\mu\text{m}$  thick
- 3 – 50  $\mu\text{m}$  thick

Sample 3:

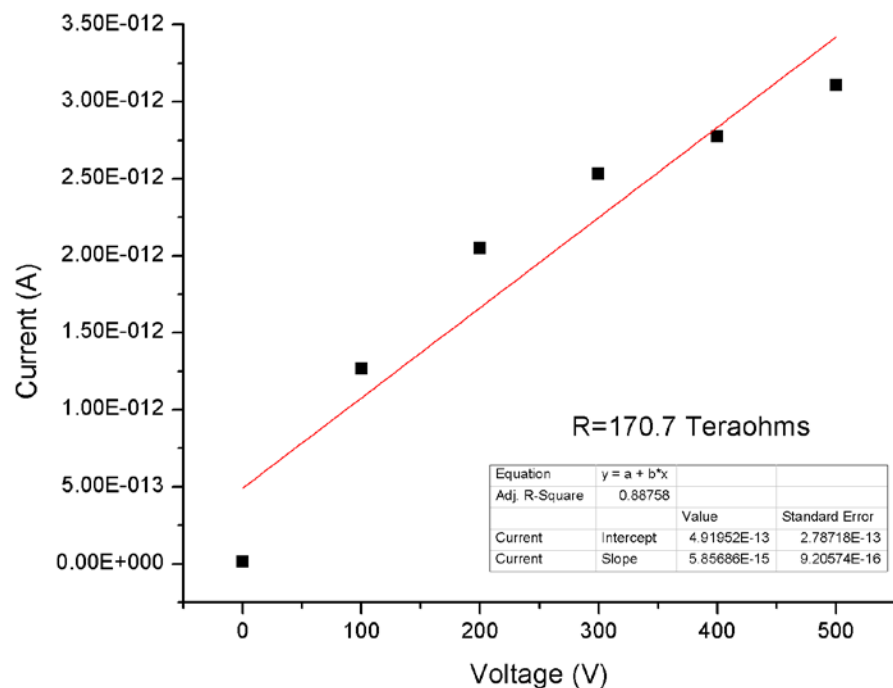
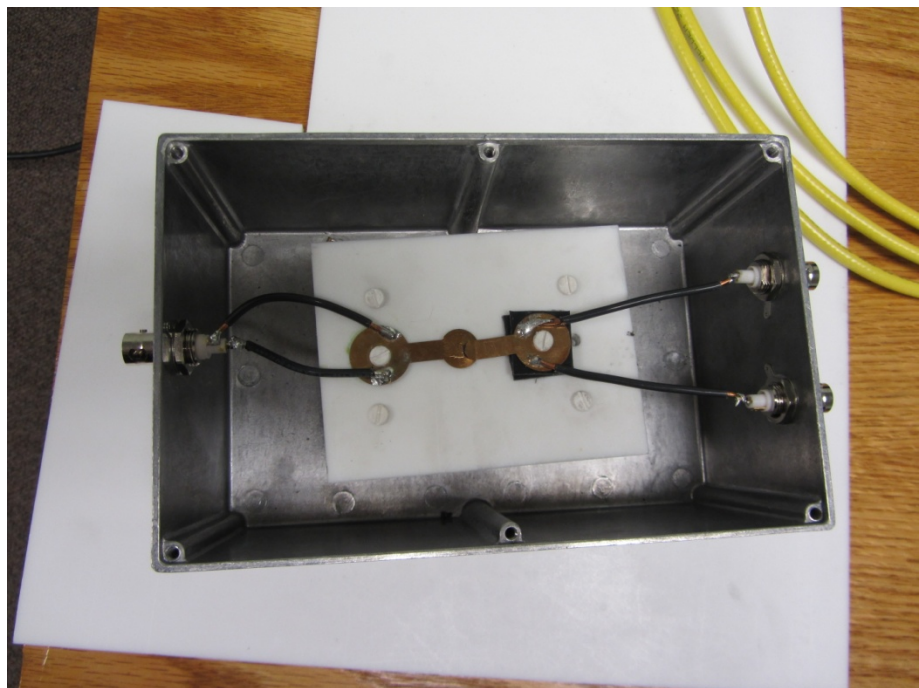
$$E_{\text{loss}} = 36 \text{ MeV}$$

trigger eff = 81% @ 100V bias



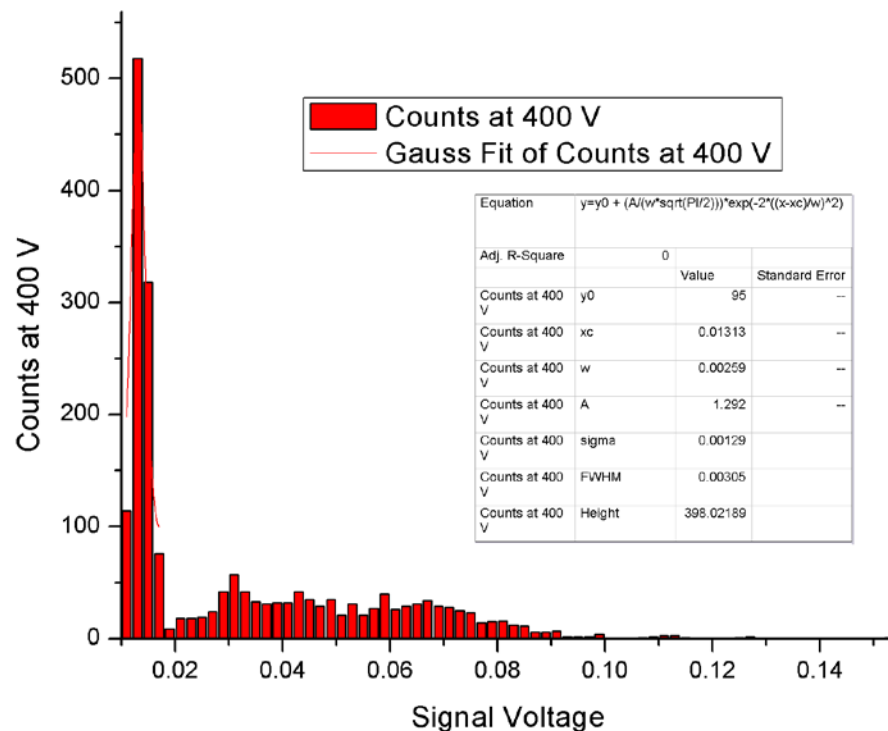
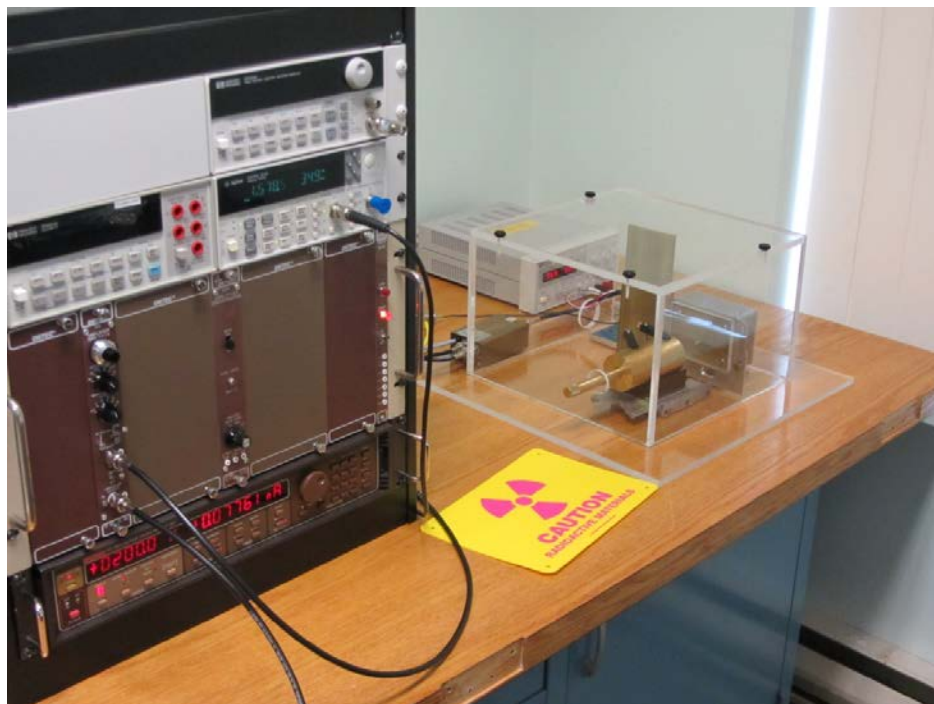
# Characterization Progress

## I-V Testing



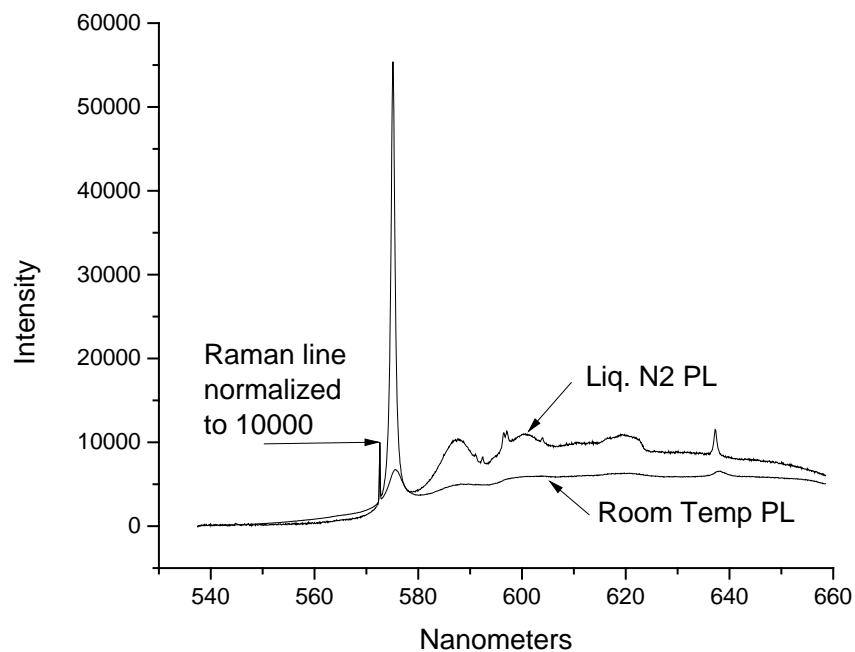
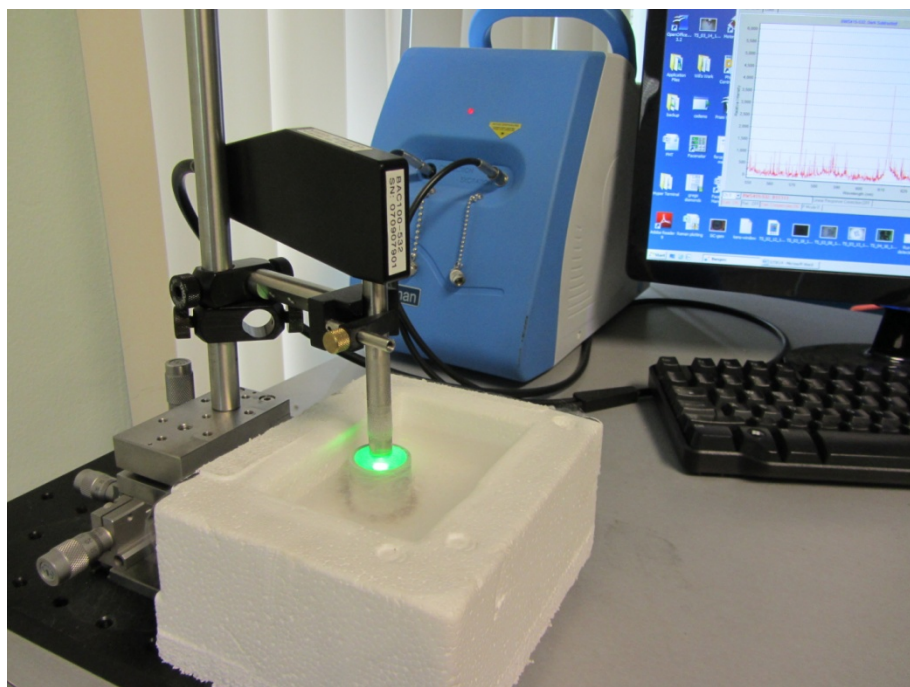
# Characterization Progress

## Charge Collection Testing

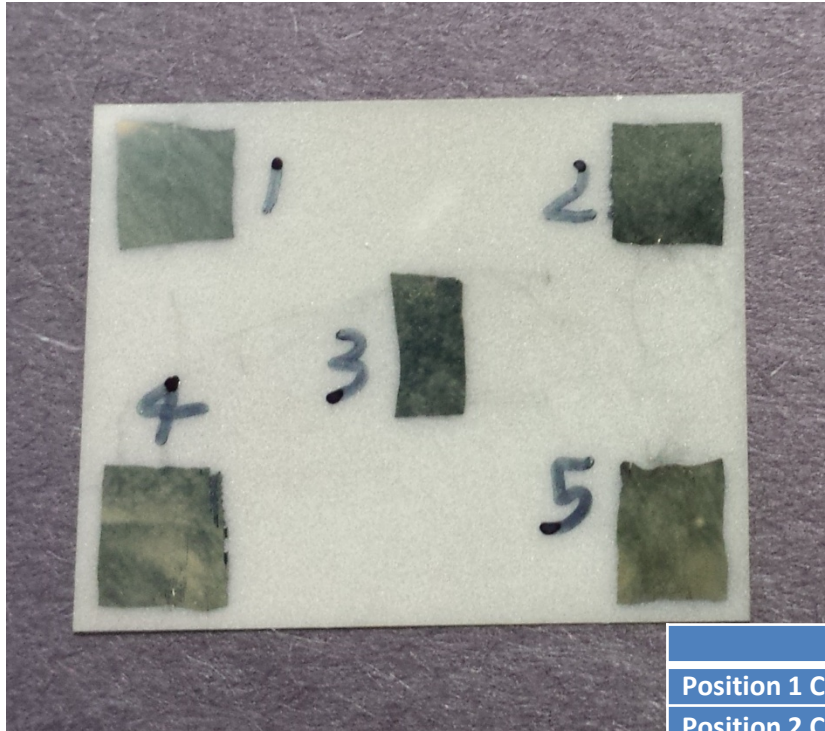


# Characterization Progress

## cryoPL Testing



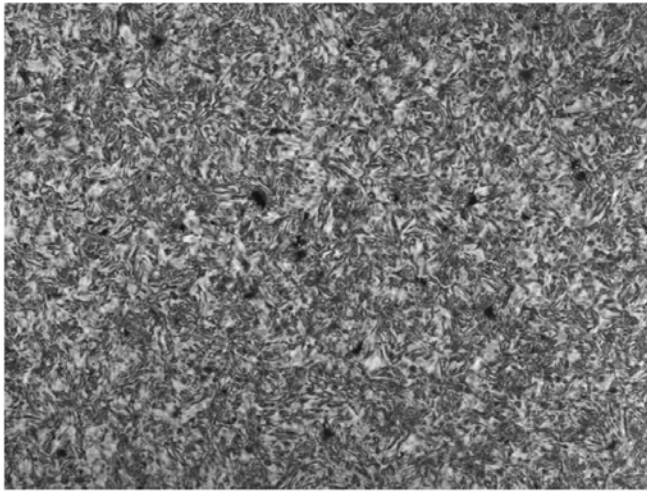
# Area Dependence of CCD



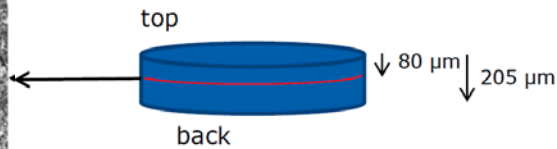
3.71% for forward bias and  
3.54% for reverse bias.

	Forward Bias	Reverse Bias
Position 1 CCD ( $\mu\text{m}$ )	12.31	12.33
Position 2 CCD ( $\mu\text{m}$ )	12.38	11.88
Position 3 CCD ( $\mu\text{m}$ )	9.64	9.11
Position 4 CCD ( $\mu\text{m}$ )	12.94	12.23
Position 5 CCD ( $\mu\text{m}$ )	13.26	12.75
Standard Deviation ( $\mu\text{m}$ )	1.28	1.30
Variance (%)	14.92	15.57

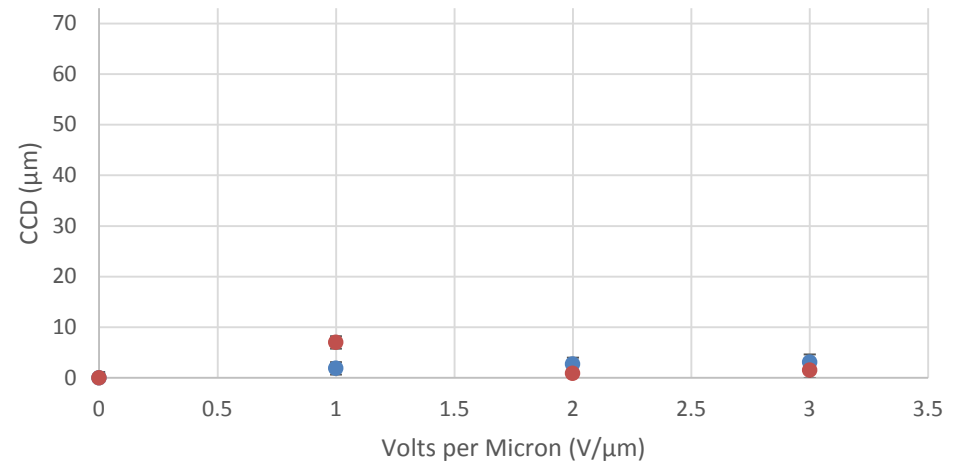
# Regrowth (Stop/Restart Run)



50  $\mu\text{m}$  original thickness  
12  $\mu\text{m}$  added



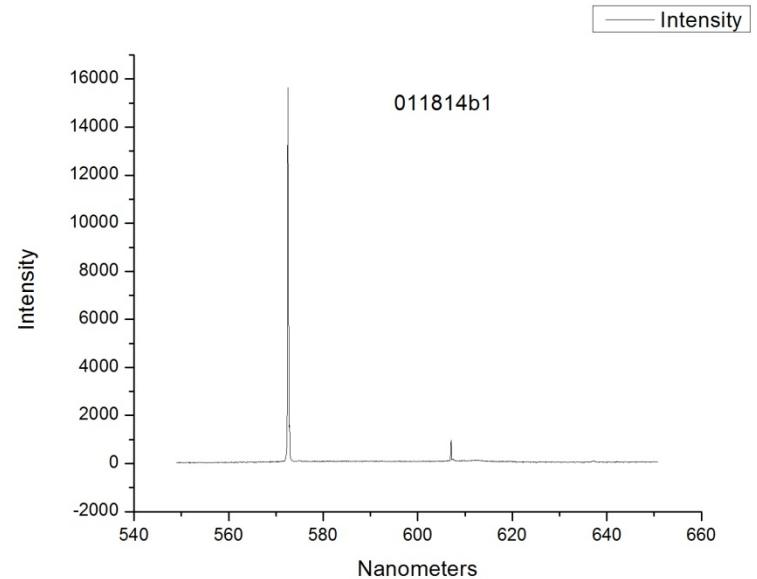
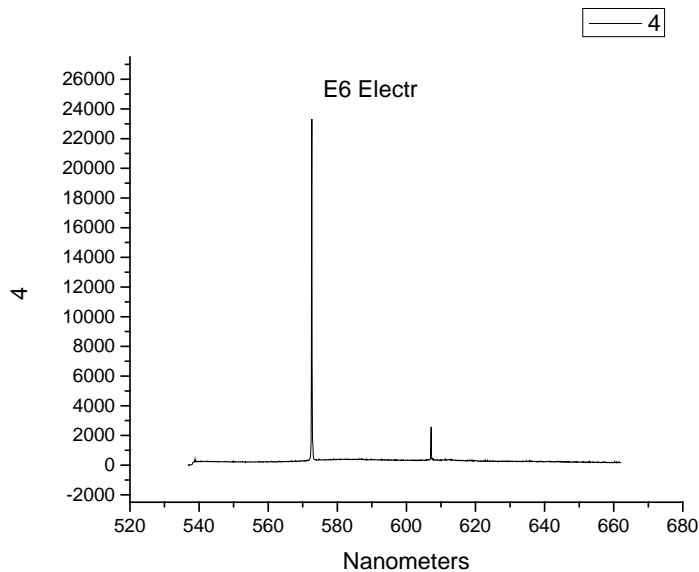
1947 CCD



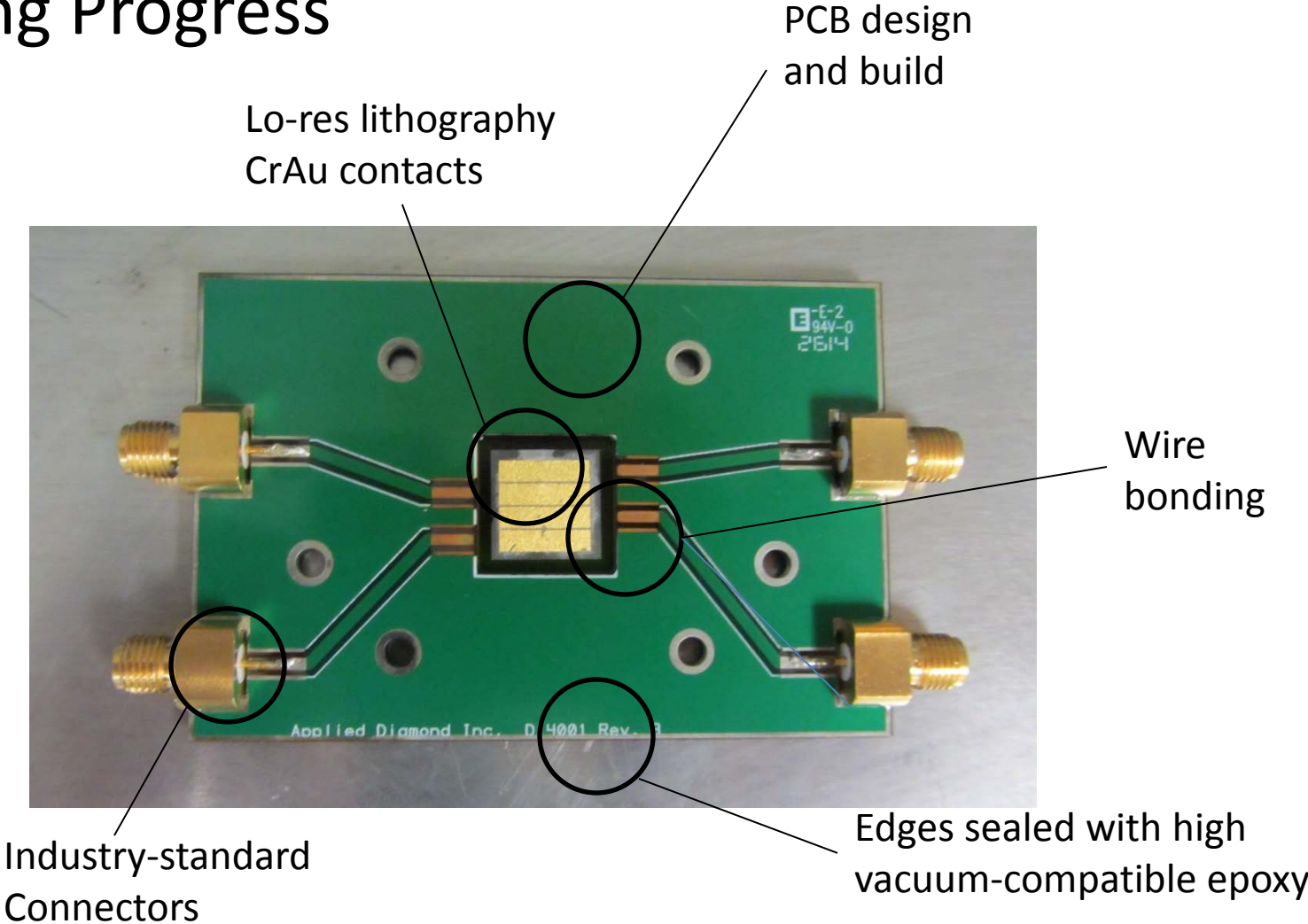
● Rough Up Forward Bias CCD ● Rough Up Reverse Bias CCD

# scCVD Growth Progress

- cryoPL shows  $NV^0$  and  $NV^-$  approaching benchmark levels

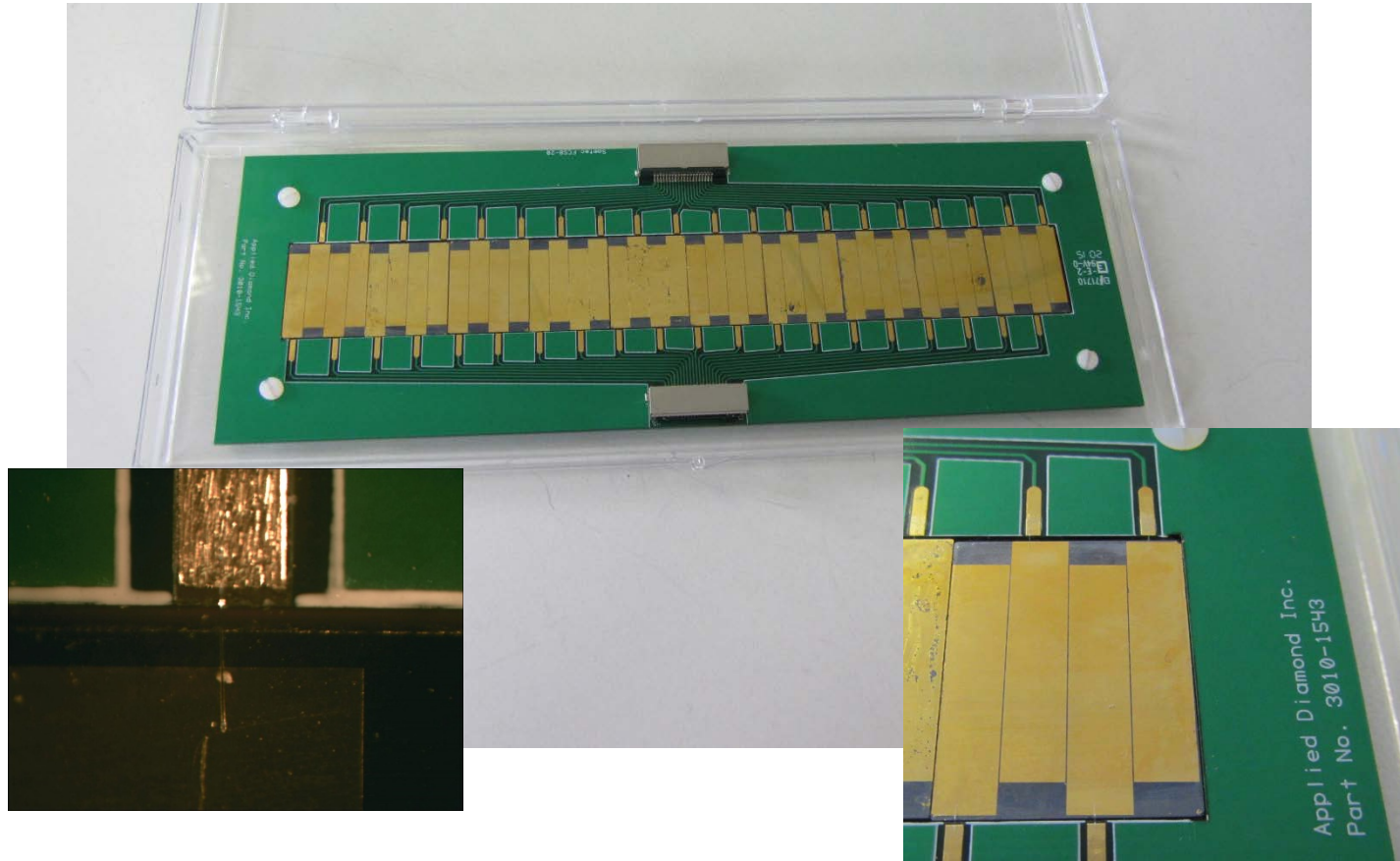


# Packaging Progress





# Packaging Progress – Focal Plane Array Board



# Commercialization Strategy

## **For scientific customers:**

- Offer both poly and sc CVD diamond for detector applications
- Develop credibility with results of characterization testing
- Provide standard and custom packaging options
- Partner in development of new detector products

## **For industrial customers:**

- Provide resource to educate and ease adoption of diamond
- Develop one-stop source for detectors using diamond

# Current Commercialization Projects

## Material Sales

- INFN – 100 electron bunches with 0.5 GeV energies
  - 2 cm sq / 50  $\mu\text{m}$  thick / 5 – 10  $\mu\text{m}$  CCD
- BNL beam position monitors
  - 4.5 mm sq / 50  $\mu\text{m}$  thick / single crystal

## Packaged Detectors

- Industrial Partner
  - Neutrons at 14 MeV
- Argonne x-ray fluorescence microscope  
(intensity indicator, normalization of signals collected from samples)
  - $10^{11}$  photons/sec at 4.5 - 25 keV

# Conclusions

- Have a process for growing thin diamond films with predictable charge collection properties.
- Have an analytical method that can reliably predict product performance in customers' applications.
- Have a process for modifying thin diamond coupons to have uniform predictable thickness coupon-to-coupon.
- Have an in-house low volume custom packaging capability.
- Sales of diamond material and prototyping of packaged detectors with end-users have started.

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